

ABSTRACT

An adhesive composition is provided that may give stable fixing strength without variation in a coated amount, and may form an adhesive film having excellent storage stability in fixing of semiconductor chips with electrode members. Moreover, an adhesive film (adhesive film for die bonding) obtained from the composition concerned is provided. An adhesive composition is used that is characterized by including epoxy resins (A), phenol resins (B), synthetic rubbers (C), and microcapsules (D) including hardening accelerator that has a core/shell structure in which a core part including hardening accelerator is covered by a shell part formed with thermoplastic resins.